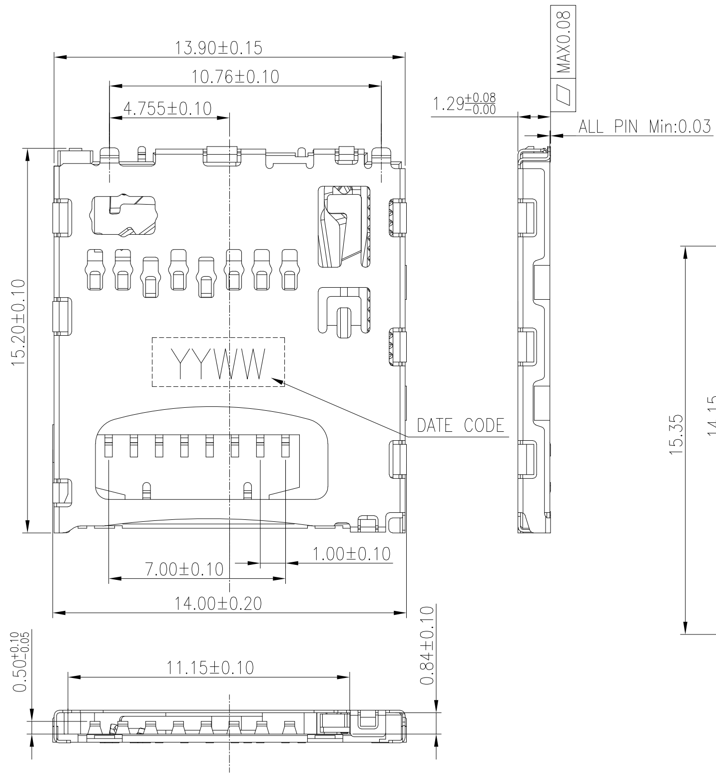
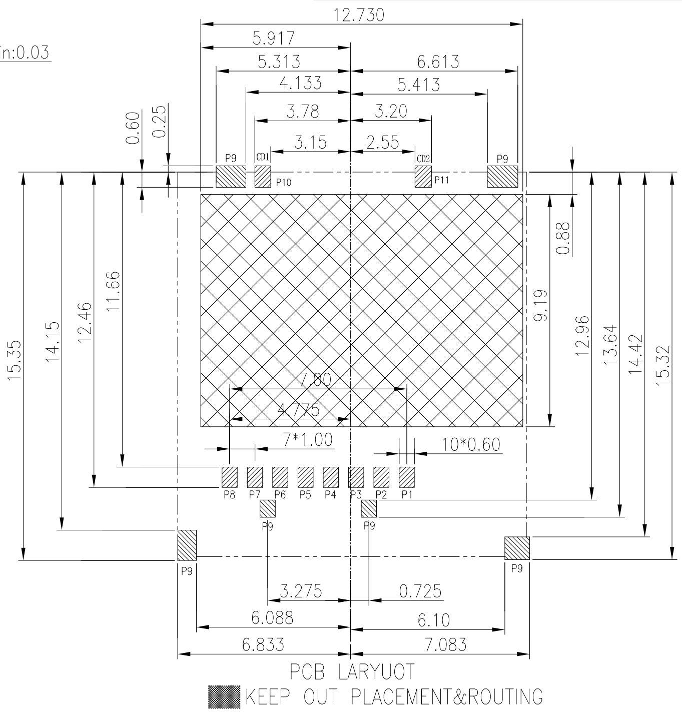
GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2014/07/21	Phebe Su
A1			Add draw and notes	2018/11/30	Summer Wang
A2			Change	2019/06/19	Phebe Su
A3			Change to insert molding structure	2019/09/16	Phebe Su





PCB LARYUOT

▩ KEEP OUT PLACEMENT&ROUTING

NOTICE:

1.Material:

Housing/Slide:HI-Temp plastic,(LCP S475/LCP E473I) UL94-V0.

Housing Color:Black

Micro-SD Terminal:Copper Alloy(C5210)

Micro-SD C/D PIN:Copper Alloy(C5210)

Cover:Stainless(SUS301)

Hook/Spring:Stainless(SWP-B)

2.PLATING:

Terminal:

Underplate:50u"Ni over all.

Solder tail:G/F over Ni.

Contact area:0.8u"Min Au over Ni.

C/D PIN:

Underplate:50u"Ni over all.

Solder tail:G/F over Ni.

Contact area:0.8u"Min Au over Ni.

Cover:

UnderplateL:30u"Ni over all.

Solder tail:G/F over Ni.

3.Solder tail coplanarity Must Be Within 0.10mm.

4.C/D:Card Detect Switch.

5.There cant be things to press and hold on the products surfase.

6.Designed And Tested In Accordance With Association Specifications

MATRIX PART NO:

MMS - 01 - 01 - 08 - 12 - 12

Matrix Micro SD

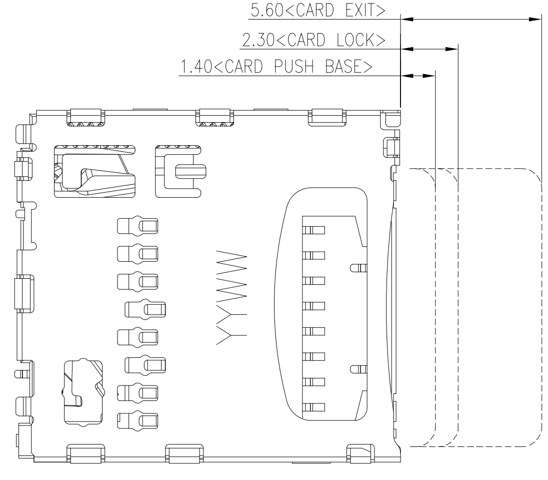
01: Push
02: Non-Push

Plating
01:G/F
30:30u

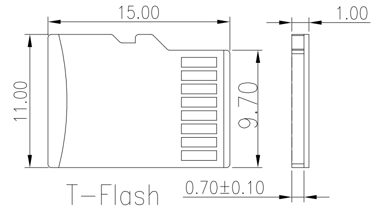
Pin number

Height

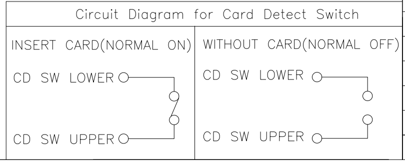
Series Number



CARD INSERT LARYUOT



Circuit Diagram for Card Detect Switch



PIN NO.	Description
Pin 1	DAT2:Data line
Pin 2	CD/DAT3:card Detect/Data line
Pin 3	CMD:command/Response
Pin 4	VDD: Supply voltage
Pin 5	CLK:Clock
Pin 6	VSS:Supply voltage ground
Pin 7	DAT0:Data line
Pin 8	DAT1:Data line
Pin 9	GND
Pin 10	COMMON
Pin 11	DETECT SW

Matrix Electronics Co.,Ltd

TOLERANCE: X. X.X ±0.30 X.XX ±0.25 X.XXX ±0.10 ANGLE: ±3°	DESIGN BY : Phebe Su	DATE : 2019/09/16	PART NAME: MICRO SD PUSH CONN
	CHECKED BY: Janice Liu	DATE : 2019/09/16	PART NO. MMS-01-01-08-12-12
	APPROVED BY1: Richard Hsieh	DATE : 2019/09/16	MOLD NO. NA
UNIT: mm [inch]	APPROVED BY2: Richard Hsieh	DATE : 2019/09/16	DRAW NO.
SCALE:1:1 SIZE:A4			SHEET NO. 1 OF 1